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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|--|-------------------------------|----------------------|------------------------|------------------|
| 10/771,817 | 06/16/2004 | John H. Magerlein | FIS9-2000-0412-US2 | 3965 |
| 7590 07/11/2006 William H. Steinberg IBM Corporation | | | EXAMINER | |
| | | | THOMAS, TONIAE M | |
| | | | ART UNIT | |
| IP Law Dept. IC | IP Law Dept. IQ0A Bldg. 040-3 | | | PAPER NUMBER |
| 1701 North Street | | | 2822 | _ |
| Endicott, NY | 13760 | | DATE MAILED: 07/11/200 | 6 |

Please find below and/or attached an Office communication concerning this application or proceeding.

| | | | 1 | | |
|---|---|---|--|--|--|
| | | Application No. | Applicant(s) | | |
| Office Action Summary | | 10/771,817 | MAGERLEIN ET AL. | | |
| | | Examiner | Art Unit | | |
| | | Toniae M. Thomas | 2822 | | |
| Period fe | The MAILING DATE of this communication apports | pears on the cover sheet wit | h the correspondence address | | |
| A SH WHII - Exte afte - If NO - Faill Any | HORTENED STATUTORY PERIOD FOR REPL CHEVER IS LONGER, FROM THE MAILING D ensions of time may be available under the provisions of 37 CFR 1.1 of SIX (6) MONTHS from the mailing date of this communication. O period for reply is specified above, the maximum statutory period ure to reply within the set or extended period for reply will, by statute or reply received by the Office later than three months after the mailing patent term adjustment. See 37 CFR 1.704(b). | DATE OF THIS COMMUNIC 136(a). In no event, however, may a re- will apply and will expire SIX (6) MONT e, cause the application to become ABA | CATION. cply be timely filed ITHS from the mailing date of this communication. ANDONED (35 U.S.C. § 133). | | |
| Status | | | | | |
| 1)🛛 | Responsive to communication(s) filed on 02 h | <i>∕ay 2006</i> . | | | |
| 2a) <u></u> ☐ | This action is FINAL . 2b)⊠ This action is non-final. | | | | |
| 3)[| Since this application is in condition for allowa | ince except for formal matte | ers, prosecution as to the merits is | | |
| | closed in accordance with the practice under the | Ex parte Quayle, 1935 C.D. | 11, 453 O.G. 213. | | |
| Disposit | tion of Claims | | | | |
| 4)⊠ | Claim(s) 1-20 is/are pending in the application | 1. | | | |
| , | 4a) Of the above claim(s) <u>20</u> is/are withdrawn from consideration. | | | | |
| 5)🖾 | Claim(s) 14-19 is/are allowed. | | | | |
| 6)⊠ | Claim(s) 1 and 3-11 is/are rejected. | | | | |
| 7)⊠ | Claim(s) 2,12 and 13 is/are objected to. | | | | |
| 8)[| Claim(s) are subject to restriction and/o | or election requirement. | • | | |
| Applicat | tion Papers | | | | |
| 9)[| The specification is objected to by the Examine | er. | | | |
| | The drawing(s) filed on <u>03 February 2004</u> is/ar | | bjected to by the Examiner. | | |
| • | Applicant may not request that any objection to the | | • | | |
| | Replacement drawing sheet(s) including the correct | | | | |
| 11) | The oath or declaration is objected to by the Ex | | • | | |
| Priority (| under 35 U.S.C. § 119 | | | | |
| | Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority document | | 119(a)-(d) or (f). | | |
| | Certified copies of the priority documents have been received in Application No | | | | |
| | 3. Copies of the certified copies of the prio | rity documents have been r | eceived in this National Stage | | |
| | application from the International Burea | u (PCT Rule 17.2(a)). | - | | |
| * (| See the attached detailed Office action for a list | of the certified copies not re | eceived. | | |
| | | | | | |
| Attachmen | • • | | | | |
| 1) Notic | ce of References Cited (PTO-892) | 4) Interview Su | | | |
| 3) 🔯 Infor | ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) er No(s)/Mail Date 02/03/04. | | /Mail Date formal Patent Application (PTO-152) | | |

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DETAILED ACTION

Election/Restrictions

- 1. Applicant's election of Group I, claims 1-19, in the reply filed on 27

 December 2005 is acknowledged. Because applicant did not traverse the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)). Claim 20 is withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected invention, there being no allowable generic or linking claim.
- 2. Applicant's traversal of the election of species filed on 02 May 2006 is persuasive. Accordingly, the election of species mailed on 07 April 2006 has been withdrawn.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1 and 3-11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Han (US 6,593,184 B2).

Han discloses a method for fabricating a semiconductor device (see figs. 2A-2E and accompanying text). The method comprises the steps of: starting with a wafer 40 (fig. 2B); forming a first interconnection structure 45 over a

first surface of the wafer (fig. 2B); forming a temporary bond between the first wafer 40 and a second wafer 31, which can be considered a wafer holder, with the wafer holder being a rigid structure (fig. 2C); thinning the wafer 40 to a desired thickness (fig. 2D and col. 3, lines 54-60); forming via holes 47 which extend through the thinned wafer with the VSTV holes having bases and substantially vertical sidewalls (fig. 2D and col. 3, lines 60-65); and forming metallization 48 in the via holes with the metallization extending through the thinned wafer (fig. 2E and col. 4, lines 1-5).

A dielectric layer 46 is formed over the thinned wafer prior to forming via holes 47 (fig. 2D and col. 3, lines 60-65).

Han does not teach forming a protective overcoat layer over the interconnection structure 45. However, it would have been obvious to one of ordinary skill in the art, at the time the invention was made, to form a protective overcoat layer over the interconnection structure 45 because the protective overcoat would protect the interconnection structure during the bonding process.

Allowable Subject Matter

4. Claims 2, 12, and 13 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The prior art of record does not anticipate, teach or suggest bonding the metallization 48 to pads of a carrier.

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5. Claims 14-19 are allowable over the prior art of record. The prior art of record does not anticipate, teach or suggest forming solder connectors, as recited in claim 14.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Toniae M. Thomas whose telephone number is (571) 272-1846. The examiner can normally be reached on Monday through Friday from 8:30 a.m. to 5:30 p.m.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

TMT 10 June 2006

> Mary Wilczewski Primary Examiner

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